

LEADED

BGA SOLDER PASTE

● ● ●
Sn63/Pb37

Melting point 183°C



Product Usage

● ● ●
TIN PASTE

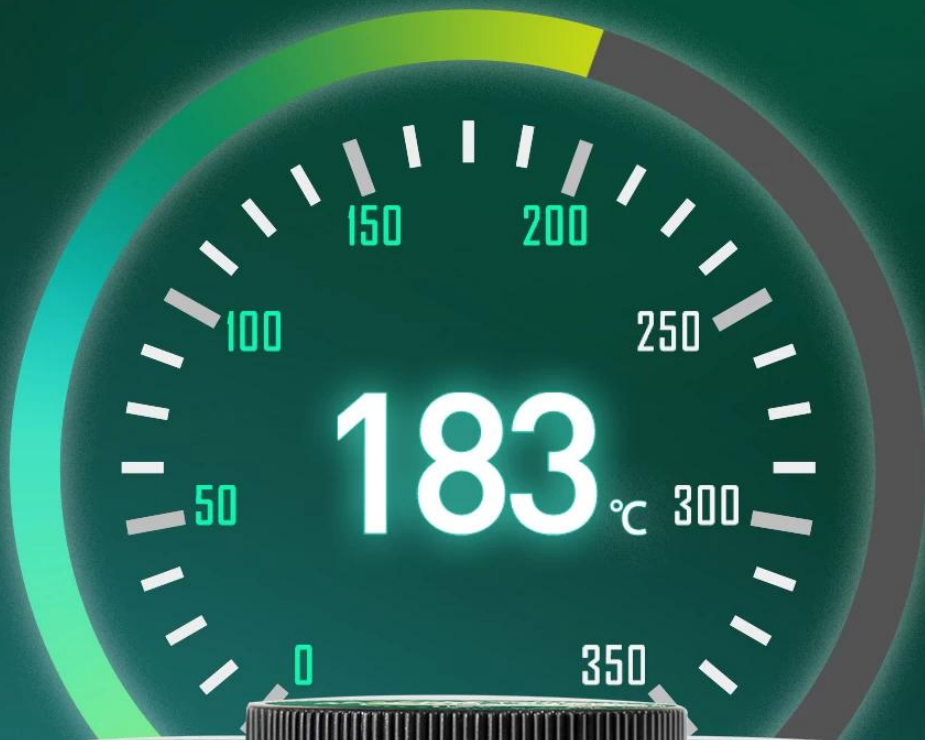
Type number	BST-506
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	50g
size	36*36mm



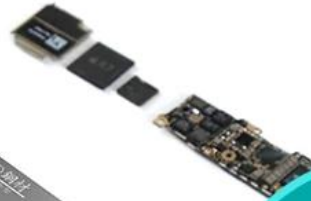
Sn63/Pb37

Melting point at medium temperature

183°C



Low residue



Solder spot bright

Rapid welding

Welding requirements for a wide range of products



SMT
patch



LED
patch



BGA
welding



Product List

G.W.:50g

